[Abstract]

Provided are a contact pin and a socket for inspection that can improve contact reliability to an IC package. An embodiment includes: an electrically conductive electrical contact 110 extending from a base end to a tip and having an elastic deformation part 112 elastically expandable and compressible in the extending direction formed between the base end and the tip; and an electrically conductive thermal contact 120 extending from a base end to a tip and having an elastic deformation part 122 elastically expandable and compressible in the extending direction formed between the base end and the tip, and the electrical contact 110 and the thermal contact 120 are laterally stacked adjacent to each other and are movable independently of each other.

Figure 6 accompanies.